

2SK2596

Silicon N-Channel MOS FET
UHF Power Amplifier

HITACHI

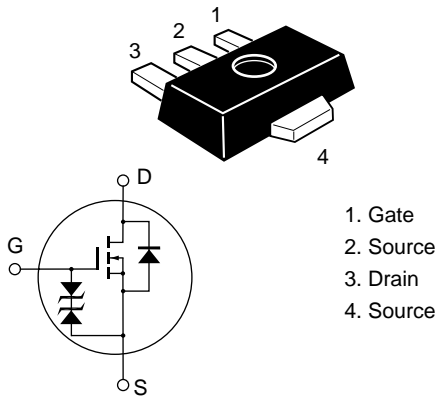
1st. Edition

Features

- High power output, High gain, High efficiency
PG = 12.2dB, Pout = 30.2dBm, $\eta_D = 45\% \text{min.}$ ($f = 836.5\text{MHz}$)
- Compact package capable of surface mounting

Outline

UPAK



This Device is sensitive to Electro Static Discharge.
An Adequate handling procedure is requested.

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	17	V
Gate to source voltage	V _{GSS}	±10	V
Drain current	I _D	0.4	A
Drain peak current	I _{D(pulse)} *1	1	A
Channel dissipation	Pch*2	3	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-45 to +150	°C

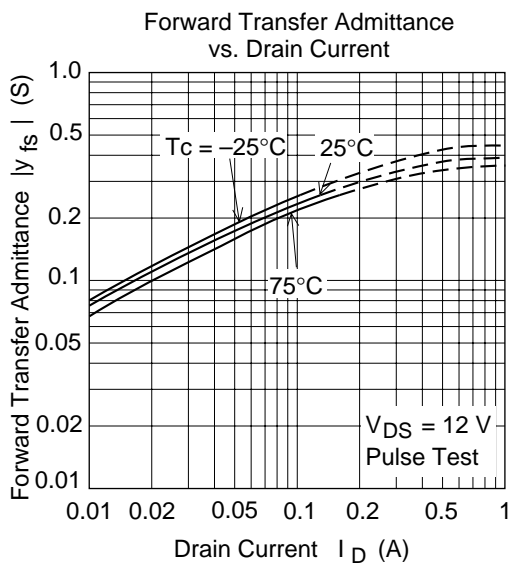
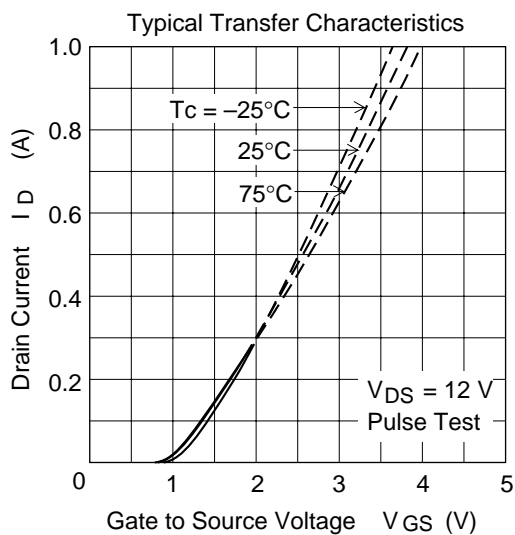
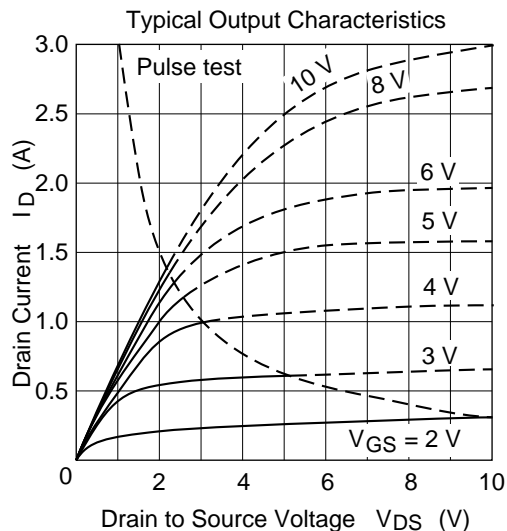
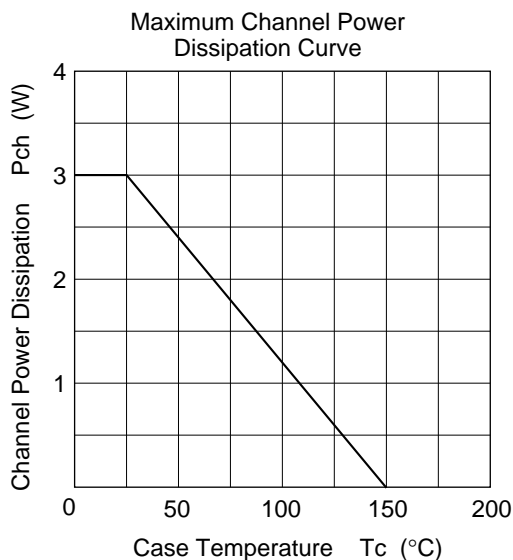
Notes: 1. PW ≤ 10μs, duty cycle ≤ 1 %

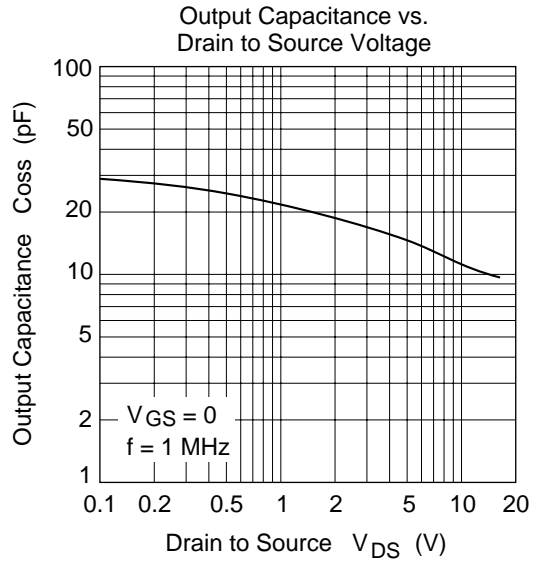
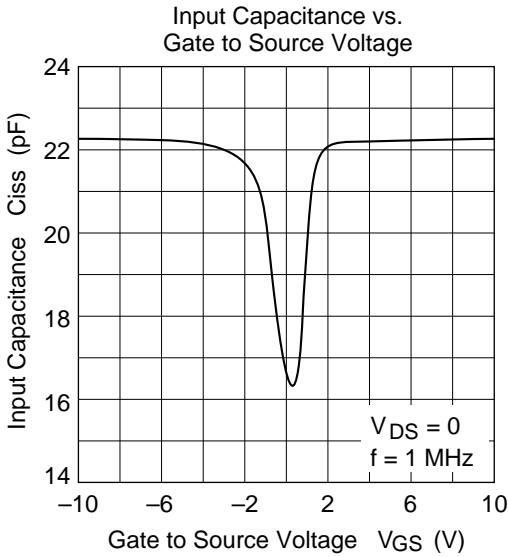
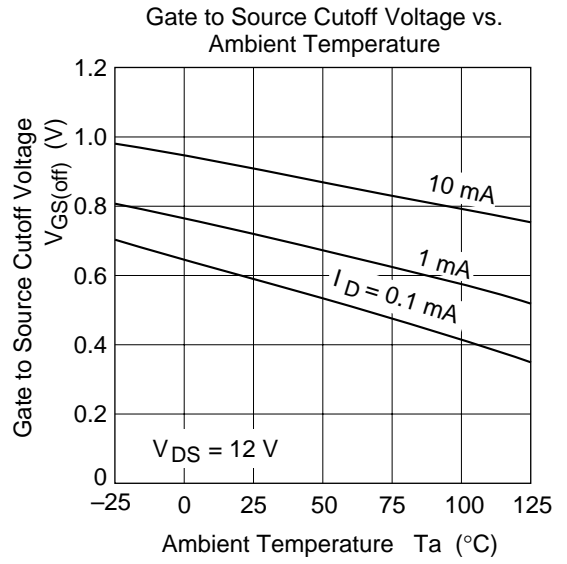
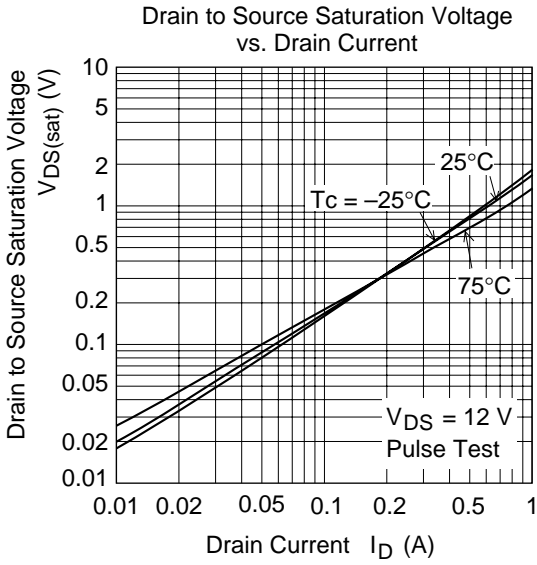
2. Value at Tc = 25°C

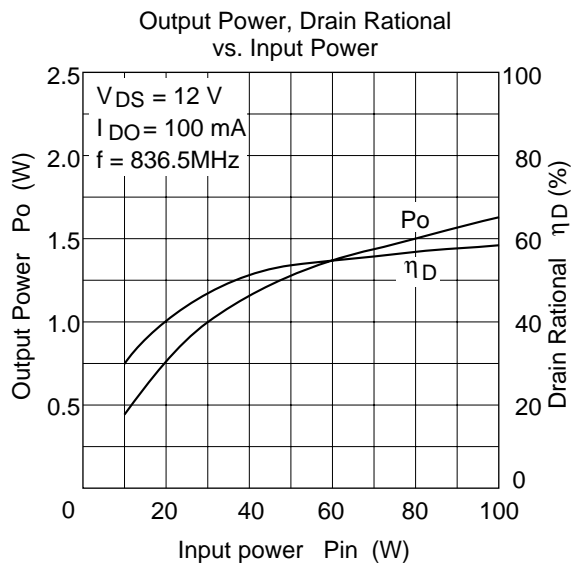
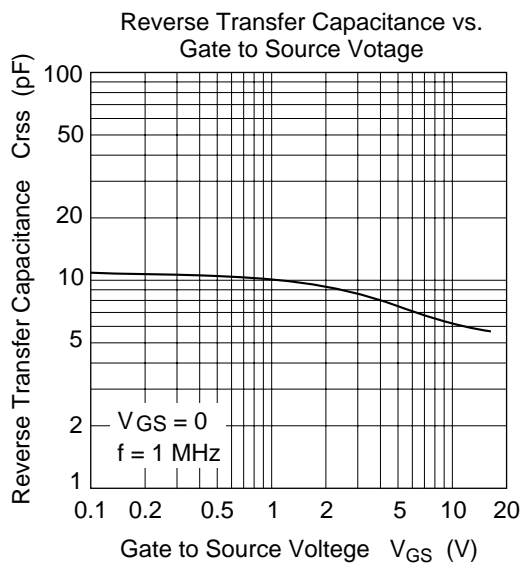
Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min.	Typ	Max.	Unit	Test Conditions
Zero gate voltage drain current	I _{DSS}	—	—	10	μA	V _{DS} = 12 V, V _{GS} = 0
Gate to source leak current	I _{GSS}	—	—	±5.0	μA	V _{GS} = ±10V, V _{DS} = 0
Gate to source cutoff voltage	V _{GS(off)}	0.4	—	1.1	V	I _D = 2mA, V _{DS} = 12V
Input capacitance	Ciss	—	22	—	pF	V _{GS} = 5V, V _{DS} = 0 f = 1MHz
Output capacitance	Coss	—	10.5	—	pF	V _{DS} = 12V, V _{GS} = 0 f = 1MHz
Output Power	Pout	30.2	31.46	—	dBm	V _{DS} = 12V f = 836.5MHz Pin = 18dBm
Drain Rational	ηD	45	55	—	%	V _{DS} = 12V Pout = 30.2dBm f = 836.5MHz Pin = 18dBm

Main Characteristics

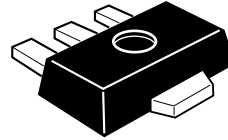
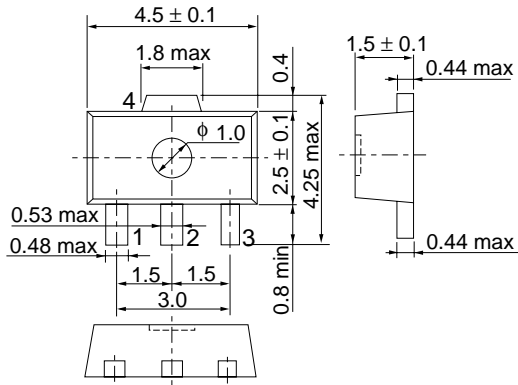






Package Dimensions

Unit: mm



Hitachi Code	UPAK
EIAJ	SC-62
JEDEC	—

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